



#### Assembly Instructions:

- 1) L1 OPEN, L3 OPEN, L4 SHORT
- 2) Q2 OPEN
- 3) C5, C13, C15, C27, C28, R11 on different pattern
- 4) R4 OPEN, R12 OPEN, R13 OPEN, R14 SHORT, R15 SHORT
- 5) C6 OPEN, C13 & C14 OPEN, C27 OPEN
- 6) D2 OPEN
- 7) D99 placed externally
- 8) Replace R6 by D100 for Vdd ORing

#### NOTES:

- 1) built on universal board PMP2773RevB
- 2) R9 for test purposes only
- 3) quiescent current in shutdown SD max. 20uA
- 4) D99, D100 only for cranking Vin < 4.5V, here 3.0V/min
- 5) max. height 8mm by L2
- 6) MLCCs only !

#### RevB2:

- 1) implemented RC snubber R101, C101 (mounted externally)
- 2) adjusted loop to max. bw due to small output cap

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